

ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR SUBSTRATE HAVING INCREASED FRACTURE
STRENGTH AND METHOD OF FORMING THE SAME

A method of processing a semiconductor substrate (50) to increase fracture strength and a semiconductor substrate (50) formed by that method. In a preferred embodiment, the semiconductor substrate (50) is utilized in a printhead (40). The semiconductor substrate (50) has a feature (60) such as an ink feed channel machined therein, and following machining the substrate is processed to remove material adjacent the machined feature to reduce micro-cracks (74) or other defects that may have been created during the feature machining process. The crack containing material may be removed by several procedures. A preferred procedure is etching with a solution containing TMAH.

(Fig. 5)